# GAE08S12 DC-DC Converter Technical Manual V1.0

Date: 2012-02-25



Eighth-Brick	36–75 V	12 V	8 A	Negative
DC-DC Converter	Input	Output	Current	Logic

## **Description**

The GAE08S12 is an isolated DC-DC converter that uses an industry-standard eighth-brick structure, and features high efficiency and power density. It has the dimensions of 9.7 mm x 22.9 mm x 57.9 mm (0.38 in. x 0.90 in. x 2.28 in.) and provides the rated output voltage of 12 V and the maximum output current of 8 A.

## **Operational Features**

Input voltage: 36–75 V

Output current: 0–8 A

· Low output ripple and noise

Efficiency: 94.1% (12 V, 8 A)

## **Mechanical Features**

- Industry standard eighth-brick (H x W x D): 9.7 mm x 22.9 mm x 57.9 mm (0.38 in. x 0.90 in. x 2.28 in.)
- Weight: about 25 g

#### **Protection Features**

- Input undervoltage protection
- Output overcurrent protection (hiccup mode)
- Output short circuit protection (hiccup mode)
- Output overvoltage protection (hiccup mode)
- Overtemperature protection (self-recovery)





**GAE08S12** 

#### **Control Features**

- Remote on/off
- Remote sense
- Output voltage trim

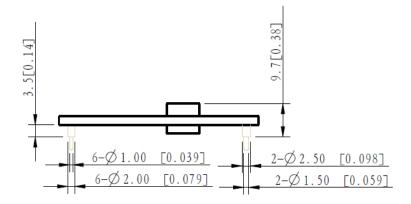
## **Safety Features**

- UL60950-1
- Underwriters Laboratory (UL) certification
- Class A requirements in EN55022 (after connecting to an external filtering circuit)
- UL94V-0
- Restriction of the use of certain hazardous substance (RoHS) 6



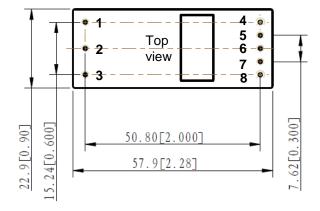
## **Mechanical Diagram**

Unit of measurement: mm (in.)



### **Pin description**

Pin No.	Function
1	V <sub>in</sub> (+)
2	CNT
3	V <sub>in</sub> (–)
4	V <sub>out</sub> (+)
5	Sense (+)
6	Trim
7	Sense (–)
8	V <sub>out</sub> (–)



#### **Dimensions tolerance**

.x	± 0.2 mm (0.008 in.)
.xx	±0.13 mm (0.005 in.)

## **Designation Explanation**

<u>G</u> <u>A</u> <u>E</u> <u>08</u> <u>S</u> <u>12</u> 1 2 3 4 5 6

1 — Isolated

2 — Analog

3 — Eighth brick

4 — Output current: 8 A

5 — Single output

6 — Output voltage: 12 V



## **Electrical Specifications**

Conditions:  $T_A = 25^{\circ}C$  (77°F), Airflow = 1.0 m/s (200 LFM), Vin = 48 V, Vout = 12 V , unless otherwise specified.

Parameter	Min.	Тур.	Max.	Units	Remarks
Absolute maximum ratings					
Input voltage Continuous Transient (100 ms)	-	-	80 100	V V	-
Operating ambient temperature	-40	-	85	°C	See the thermal derating curve.
Storage temperature	<b>-</b> 55	-	125	°C	-
Operating humidity	-	-	95	% RH	Non-condensing
Input characteristics					
Operating input voltage	36	48	75	V	-
Maximum input current	-	-	3.4	Α	V <sub>in</sub> = 0-75 V; I <sub>out</sub> = 8 A
No-load loss	-	2.4	-	W	-
Input capacitance	100	-	-	μF	Electrolytic capacitor
Inrush transient	-	-	1	A²s	-
Input reflected ripple current	-	-	20	mAp-p	-
Output characteristics					
Output voltage setpoint accuracy	11.88	12.0	12.12	V	I <sub>out</sub> = 4 A
Output power	0	-	96	W	-
Output line regulation	-	0.2	1.0	%Vo	-
Output load regulation	-	0.5	1.0	%Vo	-
Regulated voltage precision	-	-	3	%Vo	The whole range of V <sub>in</sub> and I <sub>out</sub>
Temperature coefficient	-	-	0.02	%Vo/°C	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C } (-40^{\circ}\text{F to } +185^{\circ}\text{F })$
External capacitance	220	470	5000	μF	Electrolytic capacitor
Output current	0	-	8	Α	-
Output ripple and noise	-	50	200	mVp-p	The whole range of $V_{in}$ , $I_{out}$ and $T_{A}$ ; Oscilloscope bandwidth: 20 MHz
Output voltage adjustment range(trim)	80	-	110	%Vo	-
Out voltage overshoot	-	-	5	%Vo	The whole range of $V_{in}$ , $I_{out}$ and $T_A$
Output voltage rise time	-	18.9	20	ms	The whole range of $V_{in}$ , $I_{out}$ and $T_A$
Switching frequency	-	260	-	kHz	-



## **Electrical Specifications**

Conditions:  $T_A$  = 25°C (77°F), Airflow = 1.0 m/s (200 LFM), Vin = 48 V, Vout = 12 V , unless otherwise specified.

Parameter	Min.	Тур.	Max.	Units	Remarks
Protection Features					
Input undervoltage protection Startup threshold Shutdown threshold Hysteresis	31 30 1	33.1 31.3 -	36 35 3	V V V	- - -
Output overcurrent protection	9	-	13.5	А	V <sub>in</sub> = 38-75 V; Hiccup mode
Output short circuit protection	-	-	-	-	Hiccup mode
Output overvoltage protection	14.4	15	18	V	Hiccup mode
Overtemperature protection Threshold Hysteresis	105 5	-	125 -	°C °C	Self-recovery The values are obtained by measuring the temperature of the PCB bottom near the thermal resisitor.
Dynamic Characteristics					
Overshoot amplitude Recovery time	- -	224 0	600 300	mV μs	V <sub>in</sub> = 38-75 V; Current change rate: 0.1 A/μs load: 25%–50%–25%, 50%–75%–50% Additional a 220 μF aluminum capacitor and a 1.0 μF ceramic capacitor across the load
Efficiency					
100% load	92	94.1	-	%	$V_{in} = 48 \text{ V}; I_{out} = 8 \text{ A}; T_A = 25^{\circ}\text{C} (77^{\circ}\text{F})$
50% load	91	93.1	-	%	$V_{in} = 48 \text{ V}; I_{out} = 4 \text{ A}; T_A = 25^{\circ}\text{C} (77^{\circ}\text{F})$
20% load	-	88.3	-	%	$V_{in} = 48 \text{ V}; I_{out} = 1.6 \text{ A}; T_A = 25^{\circ}\text{C} (77^{\circ}\text{F})$
Isolation characteristics					
Input-to-output Isolation voltage	-	1500	-	V DC	Basic Isolation
Other features	•		•		
Remote on/off voltage Low level High level	-0.7 3.5	-	1.2 12	V V	-
On/Off current Low level High level	-	-	1 -	mΑ μΑ	-
Reliability characteristics	Reliability characteristics				
Mean time between failures (MTBF)	-	1.5	-	Million hours	Airflow = 1.5 m/s (300 LFM); T <sub>A</sub> = 40°C (104°F); 80% load; Telcordia SR332 Method 1 case 3



## **Qualification Testing**

Parameter	Units	Condition
High Accelerated Life Test (HALT)	4	Lower operating limit: -60°C (-76°F); upper operating limit: 120°C (221°F); destruct limit: 40 G
Thermal Shock	32	500 temperature cycles between -40°C (-40°F) and +125°C (+257°F) with the temperature change rate of 20°C (68°F) per minute  Lasting for 30 minutes both at -40°C (-40°F) and +125°C (+257°F)
Temperature Humidity Bias	16	85°C (185°F); 85% RH; no load; operating 1000 hours
High Temperature Operation Life (HTOL)	16	Rated input voltage; air flow: 2.0 m/s(400 LFM); ambient temperature: 50°C(122°F); operating 1000 hours under 50%–80% load

#### **Characteristic Curves**

Figure 1: Efficiency (T<sub>A</sub> = 25°C or 77°F)

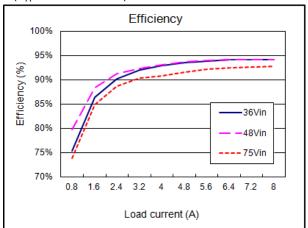


Figure 3: Thermal derating (Air is flowing from Vin to Vout;  $V_{in} = 48 \text{ V}$ ;  $V_{out} = 12 \text{ V}$ )

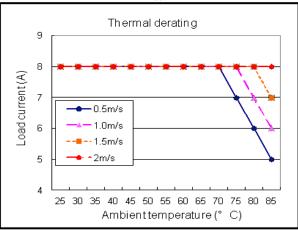


Figure 2: Power dissipation  $(T_A = 25^{\circ}C \text{ or } 77^{\circ}F)$ 

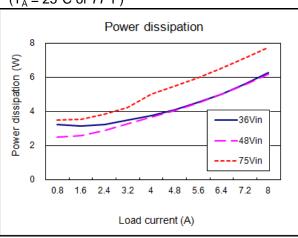


Figure 4: Thermal derating (Air is flowing from Vin(-) to Vin(+);  $V_{in} = 48 \text{ V}$ ;  $V_{out} = 12 \text{ V}$ )

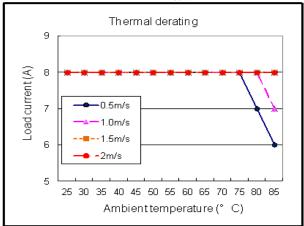




Figure 5: Thermal plot (Air is flowing from Vin to Vout;  $T_A = 25^{\circ}C$  (77°F); Airflow = 1.5 m/s (300 FLM); Vin = 48 V; Vout = 12 V; lout = 8 A)

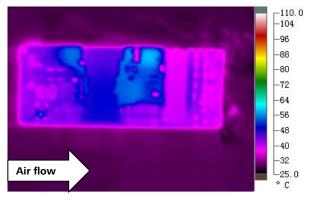
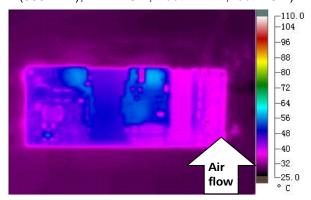


Figure 6: Thermal plot (Air is flowingfrom Vin(-) to Vin(+);  $T_A = 25$ °C (77°F); Airflow = 1.5 m/s (300 FLM); Vin = 48 V; Vout = 12 V; lout = 8 A)



## **Typical Waveforms**

Conditions:  $T_A = 25$ °C (77°F), Vin = 48 V.

Figure 7: Startup from CNT

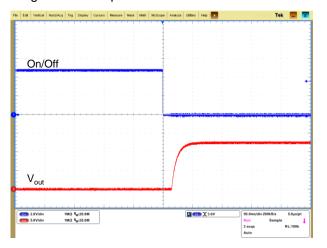


Figure 9: Startup from power on

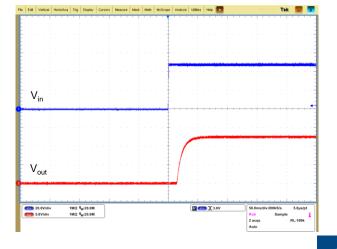


Figure 8: Shutdown from CNT

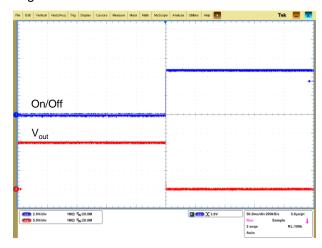


Figure 10: Shutdown from power off

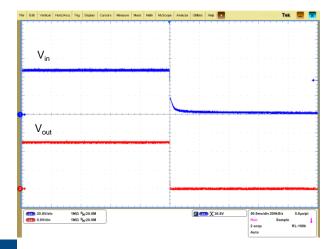




Figure 11: Output voltage response (Load: 25%–50%–25%, dl/dt=0.1 A/µs)

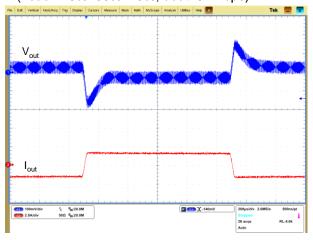


Figure 12: Output voltage response (Load 50%–75%–50%, dl/dt=0.1 A/µs)

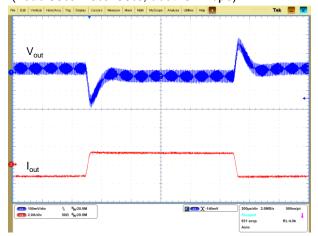
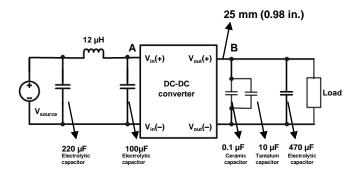


Figure 13: Test set-up diagram



## NOTE

- 1. During the test of input reflected ripple current, the input terminal must be connected to a 12  $\mu H$  inductor and a 220  $\mu F$  electrolytic capacitor.
- 2. Point B, which is for testing the output voltage ripple, is 25 mm (0.98 in.) away from the  $V_{out}(+)$  pin.

Conditions:  $T_A = 25$ °C (77°F) ,Vin = 48 V, Vout = 12 V, lout = 8 A.

Figure 14: Input reflected ripple current (for point A in the test set-up diagram)

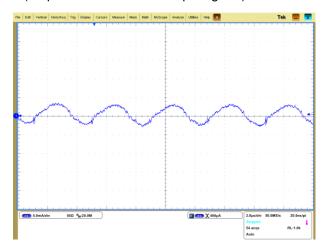
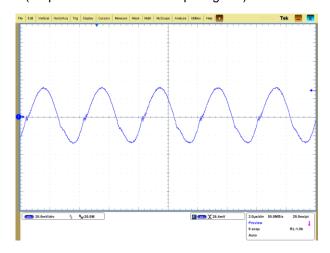


Figure 15: Output voltage ripple (for point B in the test set-up diagram)



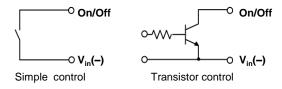


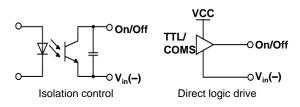
## **Feature Description**

#### Remote On/Off

Logic Enable	On/Off Pin Level	Status
Negative logic	Low level	Started
	High level or left open	Shut down

The following are some circuits for driving the on/off pin.





#### **Remote Sense**

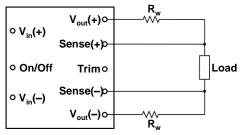
This function is used to compensate for voltage drops on circuits.

The Sense(+), Sense(-), V<sub>out</sub>(+), and V<sub>out</sub>(-) terminals should meet the following requirements:

$$[V_{out}(+) - V_{out}(-)] - [Sense(+) - Sense(-)] \le 10\%$$
 x  $V_{nom}$  ( $V_{nom}$  is the rated output voltage.)

If the remote sense function is disabled, the Sense(+) terminal connects to the V<sub>out</sub>(+) terminal and the Sense(–) terminal connects to the  $V_{out}(-)$  terminal at the output end.

Figure 16: Configuration diagram for remote sense



R<sub>w</sub> indicates the line impedance between the output end and the load.

#### Output Voltage Trim

The output voltage can be adjusted within the range of 80% V<sub>nom</sub> to 110% V<sub>nom</sub> using a trim pin.



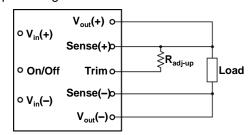
## MOTE

If the trim pin is not used, it should be left open.

#### Trim Up

The output voltage can be increased by installing an external resistor between the trim pin and the Sense(+) terminal.

Figure 15: Configuration diagram for raising the output voltage



The following formula reflects the relationship between R<sub>adj-up</sub> and V<sub>out</sub>:

$$R_{adj-up} = \frac{5.1 \times V_{nom} \times (100 + \Delta)}{1.225 \times \Delta} - \frac{510}{\Delta} - 10.2(kohm)$$

$$Where, \Delta = \frac{V_{out} - V_{nom}}{V_{vorm}} \times 100$$



#### W NOTE

Although the output voltage can be increased by both the remote sense and trim functions, the maximum increase in the output voltage is the larger value, rather than the sum of both values.

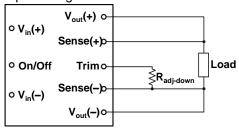
The GAE08S12 loading capability decreases as the voltage increases. Therefore, you need to ensure that the actual output power does not exceed the maximum output power when raising the voltage.

#### Trim Down

The output voltage can be decreased by installing an external resistor between the trim pin and the Sense(-) terminal.



Figure 16: Configuration diagram for lowering the output voltage



The following formula reflects the relationship between  $R_{\text{adi-down}}$  and  $V_{\text{out}}\!:$ 

$$R_{adj-down} = rac{510}{\Delta} - 10.2 (kohm)$$
 Where,  $\Delta = rac{V_{nom} - V_{out}}{V_{nom}} imes 100$ 

#### **Input Undervoltage Protection**

The GAE08S12 is shut down after the input voltage drops below the undervoltage protection threshold for shutdown. The GAE08S12 starts to work again after the input voltage reaches the input undervoltage protection threshold for startup.

#### **Output Overcurrent Protection**

When the output current exceeds the overcurrent protection threshold, the GAE08S12 works in hiccup mode until overcurrent disappears. After the output current drops to the specified range, the GAE08S12 starts to work in normal mode.

## **Output Overvoltage Protection**

When the output voltage exceeds the overvoltage protection threshold, the GAE08S12 works in hiccup mode.

### **Overtemperature Protection**

The overtemperature function protects the GAE08S12 from being damaged at high temperatures. When the GAE08S12 temperature exceeds the overtemperature protection threshold, the output is disabled. After the GAE08S12 temperature drops below the threshold, the GAE08S12 starts to work again.

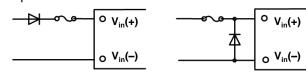
#### **MTBF**

The MTBF is calculated according to the Telcordia, SR332 Method 1 Case3. If the GAE08S12 is used at 40°C (104°F), the airflow over it can be increased to retain the MTBF.

## Recommended Reverse Polarity Protection Circuit

Reverse polarity protection is recommended under installation and cabling conditions where reverse polarity across the input may occur.

Figure 17: Recommended reverse polarity protection circuits



#### **Recommended Fuse**

The GAE08S12 has no internal fuse, but connects to an external fuse in actual use. To meet safety and regulatory requirements, a 5 A fuse is recommended.

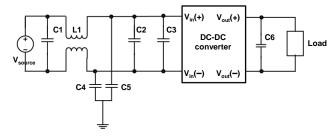


The fuse current should be 1.5 to 2 times the maximum operating current in actual use.

#### **EMC**

For the acceptance standard, see the *DC-DC* Converter EMC Acceptance Manual.

Figure 18: EMC test set-up diagram



C1: Surface mount device (SMD) ceramic capacitor (100 V/1000 nF/X7R/1210)

C2: SMD ceramic capacitor (100 V/100 nF/±10%/X7R/1206)

L1: Common-mode inductor (single phase, 1320  $\mu$ H/ $\pm$ 25%/4 A/R5K/ 21 mm x 21 mm x 12.5 mm [0.83 in. x 0.83 in. x 0.49 in.]). The chip component with the same specifications can also be used.

C4: Plug-in film safety regulation capacitor (0.022  $\mu$ F/250 V), meeting the 1 kV pressure resistance requirement.

C5: High-pressure resistant chip ceramic capacitor (22 nF/1000 V/X7R/1210). Chip ceramic capacitors are preferred.

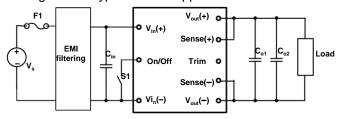
C3: Electrolytic capacitor (100 µF/100 V)

C6: Electrolytic capacitor (470 µF)



## **Typical Application**

Figure 19: Typical circuit applications



F1: 5 A fuse (fast blowing)

 $C_{in}$ : The high-frequency, low equivalent series resistance (ESR) electrolytic capacitor (100  $\mu$ F/ 100 V) is recommended.

 $C_{01}$ : The 1 uF ceramic capacitor is recommended.  $C_{02}$ : The 470 µF electrolytic capacitor is recommended.

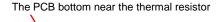


GAE08S12s cannot be connected in parallel.

#### Thermal Consideration

Sufficient airflow should be provided to help ensure reliable operating of the GAE08S12. Therefore, thermal components are mounted on the top surface of the GAE08S12 to dissipate heat to the surrounding environment by conduction, convection and radiation. Proper airflow can be verified by measuring the temperature at the PCB bottom near the thermal resistor.

Figure 20: Thermal test point





## NOTE

The temperature at the thermal test point on the GAE08S12 cannot exceed 105°C (221°F). Otherwise, the GAE08S12 will be protected against overtemperature and will not operate properly.

#### **Power Dissipation**

The GAE08S12 power dissipation is calculated based on efficiency. The following formula reflects the relationship between the consumed power ( $P_d$ ), efficiency ( $\eta$ ), and output power ( $P_o$ ):  $P_d = P_o(1-\eta)/\eta$ 

#### **Mechanical Considerations**

#### Installation

Although the GAE08S12 can be mounted in any direction, free airflow must be taken. Normally power components are always installed at the end of the airflow path or have separate airflow paths. The installation mode helps keep other system equipment cooler and increase component service life.

#### Soldering

The GAE08S12 is compatible with standard wave soldering techniques. During wave soldering, the setting parameters should base on the speciality of using flux, such as the preheating temperature and time, the soldering temperature and time and so on. To improve the soldering heighten, it is allowed to improve the preheating and soldering temperature, prolong the preheating and soldering time as the larger thermal capacity of the module. However, it is not allowed to excess the high temperature limitation of the components that belong to the module.

When soldering the GAE08S12, ensure that the soldering iron is at 425°C (797°F) and contacts pins for a maximum of 3 seconds, because long-time soldering at high temperatures may cause the GAE08S12 interior to be damaged. The GAE08S12 can be rinsed using the isopropyl alcohol (IPA) solvent or other proper solvents.

#### **HUAWEI TECHNOLOGIES CO., LTD.**

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